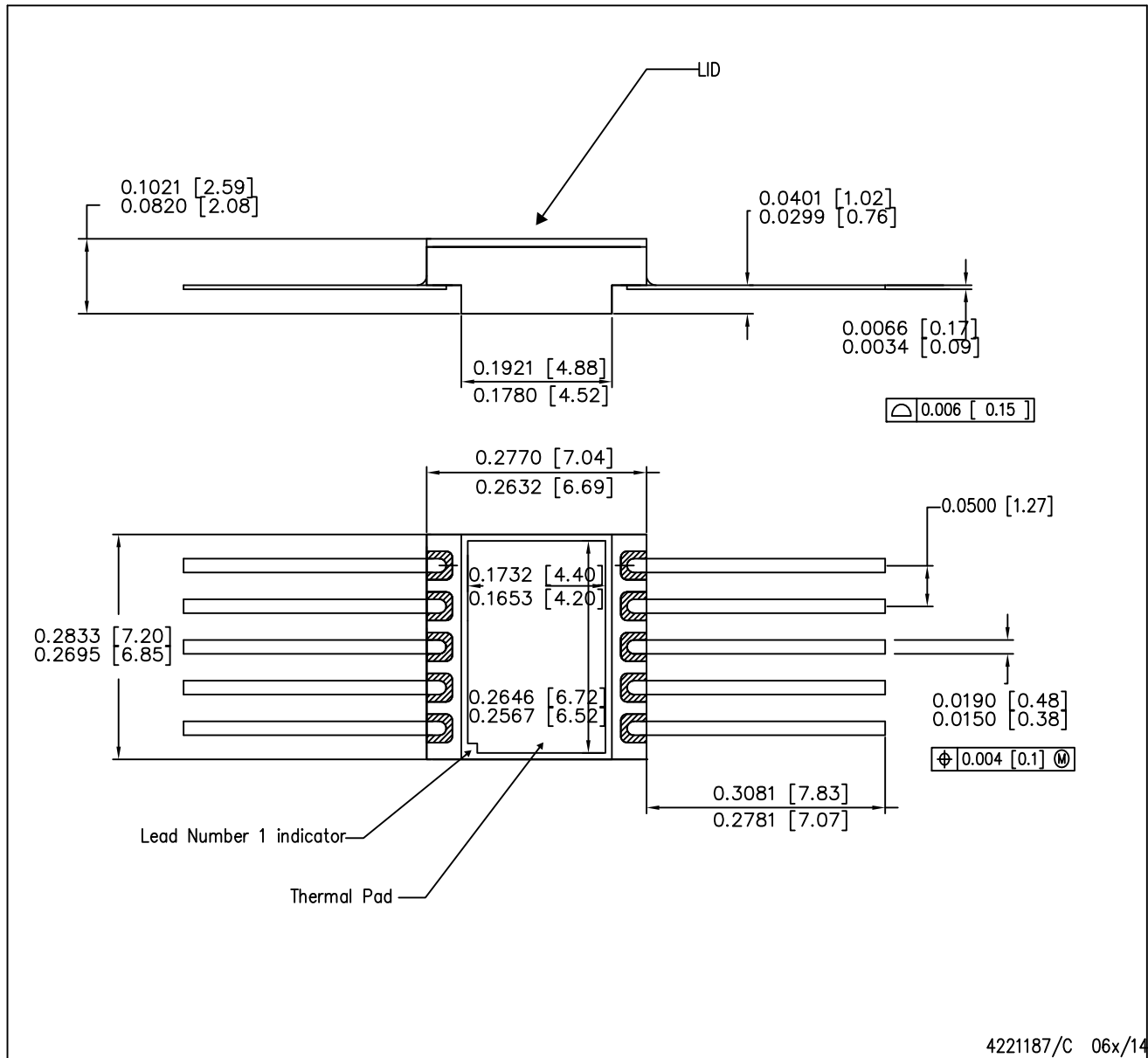


HKU (R-CDFP-F10)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This drawing does not comply with Mil Std 1835. Do not use this package for compliant product.
 - D. The terminals will be gold plated.

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